EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2	("20040082186").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/16 10:43
S2	6	(@ad<="20021014") and ((dummy or seasoning) with wafer) and clean$3 and etch$3 and (deo with duy)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/26 15:10
S3	0	(@ad<="20021014") and ((dummy or seasoning) with wafer) and clean$3 and etch$3 and (deo with duy) and (BCI3 or "BCl.sub.3")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/02 14:46
S4	3	(@ad<="20021014") and ((dummy or seasoning) with wafer) and clean$3 and etch$3 and (deo with duy) and (metal)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/02 16:39
S5	2	("6872322").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/16 14:18
S6	6	(("6872322") or ("6765400") or ("6566270")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/16 14:20
S7	6	(("6872322") or ("6765400") or ("6566270")).PN.	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/16 14:21
S8	3	(("6872322") or ("6765400") or ("6566270")).PN.	USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/10/16 14:21

S9	6	(("6872322") or ("6765400") or ("6566270")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/16 14:23
S10	2	S8 and tungsten	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/16 14:24
S11	3	(("6872322") or ("5765400") or ("6566270")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/10/16 14:25
S12	2	S10 and tungsten	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/16 14:26
S13	3	(("6872322") or ("5756400") or ("6566270")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/10/16 14:25
S14	1	S13 and tungsten	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/16 14:26
S15	2	("5756400").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/25 17:17
S16	2	("6566270").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/25 17:17
S17	3	(("6872322") or ("6765400") or ("6566270")).PN.	USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/10/26 09:05
S18	7832	ye.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/26 09:05

S19	175	(@ad<="20021014") and ((dummy or seasoning) with wafer) and ((clean$3 with chamber) same (Cl2 or "cl. sub.2" or chlorine or fluorine))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/26 15:18
S20	75	(@ad<="20021014") and ((dummy or seasoning) with wafer) and ((clean$3 with chamber) same (Cl2 or "cl. sub.2" or chlorine))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/26 16:41
S21	2	("20040082186").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/04/26 16:09
S22	15	(@ad<="20021014") and ((dummy or seasoning) with wafer) and ((clean$3 with chamber) same ((Cl2 or "cl. sub.2" or chlorine) with (cf4 or cf.sub.4")))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/27 10:57
S23	66655	(@ad<="20021024") and semiconductor and insulat$3 and conductive and etch$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/27 11:02
S24	12069	(@ad<="20021024") and "semiconductor layer" and insulat$3 and conductive and etch$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/30 08:57
S25	3685	(@ad<="20021024") and ("semiconductor layer" same insulat$3 same conductive) and etch$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/27 11:03
S26	753	(@ad<="20021024") and ("semiconductor layer" same insulator same conductive) and etch$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/25 12:14
S27	2	"20020137352"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/30 08:13

S28	6	(US-20040082186-$ or US-20020162827-$ or US-20030222306-$ or US-20020137352-$).did. or (US-6566270-$ or US-6872322-$).did.	US-PGPUB; USPAT	OR	ON	2007/04/30 08:33
S29	1	S28 and (brom$4 or bcl$4)	US-PGPUB; USPAT	OR	ON	2007/04/30 08:33
S30	28	(@ad<="20021024") and (tungsten with etch$3 with (cl2 or "cl.sub.2") with (SF6 or "sf.sub.6") with (o2 or "o.sub.2" or oxygen))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/30 10:27
S31	4926	(@ad<="20021024") and ("second conductive" with etch$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/30 10:29
S32	33	(@ad<="20021024") and ("second conductive" with etch$3 and bromine)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/30 11:22
S33	2	("20050056615").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/04/30 11:22
S34	84	(@ad<="20021014") and ((dummy or seasoning) with wafer with quartz)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/02 14:46
S35	83	(@ad<="20021014") and ((dummy) with wafer with quartz)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/02 14:46
S36	64	(@ad<="20021014") and (("dummy wafer") with quartz)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/02 14:54

S37	3	(@ad<="20021014") and (("dummy wafer") with quartz with clean$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/02 14:49
S38	1	(@ad<="20021014") and (("dummy wafer") with quartz with clean$4 with etch$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/02 14:49
S39	11	(@ad<="20021014") and (("dummy wafer" with quartz) same etch$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/02 16:32
S40	2	("20020121502").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/05/02 16:32
S41	2651	(@ad<="20021014") and (etch$3 with (BCl3 or "BCl.sub.3"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/02 16:40
S42	24	(@ad<="20021014") and (etch$3 with conductor with (BCl3 or "BCl.sub.3"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/02 16:41
S43	2	("20040082186").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 08:54
S44	49	(@ad<="20021024") and ("semiconductor layer" same insulator same conductive) and ((first near2 etch$3) same (second near2 etch$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/25 12:15
S45	34	(@ad<="20021024") and ("semiconductor layer" same insulator same conductive) and ((first near2 etch$3) same (second near2 etch$3)) and gate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/25 12:15

S46	4	(("5756400") or ("20020053764")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/26 11:35
S47	4	(("5756400") or ("20020053674")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/26 11:35
S48	30	("20020048829" | "20020053674" | "20020137352" | "20020162827" | "20030222306" | "20050056934" | "20050266593" | "5756400" | "6093457" | "6274500" | "6352081" | "6352081" | "6566270" | "6815359" | "6842658" | "6872322").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/04/15 10:25
S49	0	(@ad<="20021024") and S48 and (BO or (boron adj1 oxide))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/15 11:06
S50	0	(@ad<="20021024") and S48 and (BO or (boron adj3 oxide))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/15 11:07
S51	0	(@ad<="20021024") and S48 and (BO or (boron adj3 oxide) or "BO.sub.$")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/15 11:11
S52	0	S48 and (BO or (boron adj3 oxide) or "BO.sub.$")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/15 11:11
S53	0	S48 and (BO or (boron adj3 oxide) or ("BO.sub."$))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/15 11:51

S54	1	S48 and (BO or (boron with oxide) or ("BO.sub."$))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/15 11:51
S55	1	S48 and (BO or (boron with oxide) or ("BO.sub.x"$))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/15 11:51
S56	1	S48 and (BO or (boron with oxide) or ("BO.sub.2"$))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/15 11:51
S57	1	S48 and (BO or (boron with oxide) or ("BO.sub.3"$))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/15 11:52
S58	13950	(@ad<="20021014") and (BO or (boron adj3 oxide) or ("BO.sub."$)) and (clean or cleaning or removing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/08 08:46
S59	578	(@ad<="20021014") and ((BO or (boron near3 oxide) or ("BO.sub."$)) with (clean or cleaning or removing))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/08 08:48
S60	198	(@ad<="20021014") and ((BO or (boron near3 oxide) or ("BO.sub."$)) with (clean or cleaning or removing)) and plasma	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/08 08:48
S61	61	(@ad<="20021014") and ((BO or (boron near3 oxide) or ("BO.sub."$)) with (clean or cleaning or removing)) and plasma not "BOE"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/08 08:49
S62	2	(@ad<="20021014") and ((BO or (boron near3 oxide) or ("BO.sub."$)) with (clean or cleaning or removing) with plasma) not "BOE"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/08 09:06

S63	2	(@ad<="20021014") and (((BO or (boron near3 oxide) or "BO.sub."$)) with (clean or cleaning or removing) with plasma)) not "BOE"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/08 09:07
S64	0	(@ad<="20021014") and (("B.sub.2O.sub.3" with (clean or cleaning or removing) with plasma)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/08 09:29
S65	50	(@ad<="20021014") and (("B.sub.2O.sub.3" or BOx or "BO.sub.x" or "B.sub.xO.sub. y") with (clean or cleaning or removing) with plasma)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/08 09:30
S66	0	(@ad<="20021014") and (("B.sub.2O.sub.3" or "BO. sub.x" or "B.sub.xO.sub.y") with (clean or cleaning or removing) with plasma)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/08 09:31
S67	3	(@ad<="20021014") and (("B.sub.2O.sub.3" or "BO. sub.x" or "B.sub.xO.sub.y" or (boron near2 oxide)) with (clean or cleaning or removing) with plasma)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/08 09:32
S68	6	(@ad<="20021014") and ((("B.sub.2O.sub.3" or "BO. sub.x" or "B.sub.xO.sub.y" or (boron near2 oxide)) with (clean or cleaning or removing)) same plasma)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/08 09:33
S69	509	(@ad<="20021014") and (clean$3 with chamber with between with steps)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/08 09:39
S70	72	(@ad<="20021014") and (clean$3 with chamber with between with steps with etch $3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/08 09:40
S71	2	(@ad<="20021014") and (clean$3 with chamber with between with steps with etch $3 with dummy)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/08 09:49

S72	2	("20030207585").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/09 16:33
S73	2503	(438/706).ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/10 10:44
S74	222	(438/707).ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/10 10:44
S75	723	(438/705).ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/10 10:44
S76	1216	(438/723).ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/10 10:45
S77	1418	(438/16).ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/10 10:45
S78	1883	(438/710).ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/10 10:46
S79	188	(438/721).ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/10 10:46
S80	1216	(438/723).ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/10 10:46

S81	9396	(okamoto-S$).in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/10 10:48
S82	299	(okamoto-Satoru).in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/10 10:48
S83	1	(okamoto-Satoru).in. and (BOx or "BO.sub.x").clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/10 10:49

7/27/2009 5:55:54 PM
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